

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JAE YOUNG LEE	05/26/2020
JI WON JUNG	05/26/2020
RECEIVING PARTY DATA	
Name:	SAMSUNG SDS CO., LTD.
Street Address:	(SINCHEON-DONG) 125, OLYMPIC-RO 35-GIL, SONGPA-GU,
City:	SEOUL
State/Country:	KOREA, REPUBLIC OF
Postal Code:	05510
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16883343
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	571-249-5652
Email:	mail@thepllaw.com
Correspondent Name:	THE PL LAW GROUP, PLLC
Address Line 1:	13800 COPPERMINE ROAD
Address Line 2:	FL 1-3
Address Line 4:	HERNDON, VIRGINIA 20171
ATTORNEY DOCKET NUMBER:	Q31820DH18
NAME OF SUBMITTER:	JONG H PARK
SIGNATURE:	/JONG H PARK/
DATE SIGNED:	05/26/2020
Total Attachments: 1	
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ASSIGNMENT

AS A BELOW NAMED INVENTOR, I, and each of us, individually hereby declare that
IN CONSIDERATION of the sum of TEN (\$10.00) dollars or the equivalent thereof, and other good and valuable
consideration, the receipt of which from the hereinafter named Assignee is hereby acknowledged, I do hereby
sell, assign and forever grant and convey unto:

SAMSUNG SDS CO., LTD.

having an address at (Sincheon-dong) 126, Olympic-ro 35-gil, Songpa-gu, Seoul 05510, Republic of Korea

Who is my Assignee, and to the successors and assigns of my Assignee, all my right, title and
interest, in and for the United States of America and all other countries, including all rights of priority, in and to
the invention entitled:



APPARATUS AND METHOD FOR CONSTRUCTING PARAMETERIZED QUANTUM CIRCUIT

invented by me and described in an application for a United States patent the specification of which is either
attached hereto or otherwise accompanies this Assignment and in and to all United States patents which may
be granted thereon and therefore, and in and to all certificates of corrections, divisions, continuations,
continuations-in-part, reissued and re-examined patents, and to any extensions thereof, said interest being the
entire ownership of the patent when granted, to be held and enjoyed by **SAMSUNG SDS CO., LTD.**, my
Assignee, its successors, assigns or other legal representatives, to the full end of the term, terms, or any
extension or renewal thereof, for which said patent or patents may be granted, as fully and entirely as the same
would have been held and enjoyed by me or us if this assignment, sale and conveyance had not been made;

AND I hereby covenant and agree to sign and execute, without receiving any money or other
consideration, any further documents or instruments which may from time-to-time be either necessary, lawful,
proper or requested by the Assignee, in the prosecution of the above-named application or in the preparation
and prosecution of all substitute applications, certificate of correction, division, continuation, continuation-in-
part, reissue, re-examination, in any amendment, extension, or interference proceeding, whether administrative
or judicial, or otherwise, to secure the title hereto in said Assignee, together with the right of priority under the
International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents,
Designs and Industrial Models, and any other international agreement or treaty to which the United States of
America adheres.

I hereby authorize and request the Patent Office Officials in the United States and its territorial
possessions and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said
my Assignee.

IN WITNESS WHEREOF, I have set our hands and seals on the dates written beside my name.

Legal Name of First Inventor: LEE, Jae Young	
Inventor's Signature: 	Date: May 26, 2020
Legal Name of Additional Inventor: JUNG, Ji Won	
Inventor's Signature: 	Date: May 26, 2020

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